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Version with markings to show changes made

In the claims:

Claims 3-7, 11, 13-15, 21, and 23-26 have been amended as follows:

1. (Reiterated) Electronic component, particularly a surface-mountable radiation-emitting and/or radiation-sensitive electro-optical component (1), with a plastic housing (10) that includes at least one metallic soldering area (4), characterized in that the surface of the plastic housing (10), except for the metallic soldering area (4), is at least partially covered by an anti-solder coating (6).
2. (Reiterated) Electronic component as in Claim 1, characterized in that the anti-solder coating (6) essentially consists of siloxane.
3. (Amended) Electronic component as in Claim 1 [or 2], characterized in that the anti-solder coating (6) essentially consists of polysiloxane.
4. (Amended) Electronic component as in [one of the previous Claims] claim 1, characterized in that the anti-solder coating (6) is essentially based on methyl-polysiloxane.
5. (Amended) Electronic component as in [one of the previous Claims] claim 1, characterized in that the anti-solder coating (6) is essentially based on dimethyl-polysiloxane.
6. (Amended) Electronic component as in [one of the previous Claims] claim 1, characterized in that the anti-solder coating (6) is essentially based on polyether-modified dimethyl-polysiloxane.
7. (Amended) Electronic component as in [one of the previous Claims] claim 1, characterized in that the plastic housing (14) contains a radiation-emitting and/or radiation-detecting semi-conductor element that is embedded in transparent plastic for the emitted and/or received radiation.

